

19A, 55V, 0.070 Ohm, N-Channel UltraFET Power MOSFETs



These N-Channel power MOSFETs are manufactured using the innovative UltraFET® process. This advanced process technology

achieves the lowest possible on-resistance per silicon area, resulting in outstanding performance. This device is capable of withstanding high energy in the avalanche mode and the diode exhibits very low reverse recovery time and stored charge. It was designed for use in applications where power efficiency is important, such as switching regulators, switching converters, motor drivers, relay drivers, low-voltage bus switches, and power management in portable and battery-operated products.

Formerly developmental type TA75309.

Ordering Information

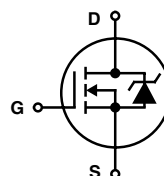
PART NUMBER	PACKAGE	BRAND
HUF75309P3	TO-220AB	75309P
HUF75309D3	TO-251AA	75309D
HUF75309D3S	TO-252AA	75309D

NOTE: When ordering, use the entire part number. Add the suffix T to obtain the TO-252AA variant in tape and reel, e.g., HUF75309D3ST.

Features

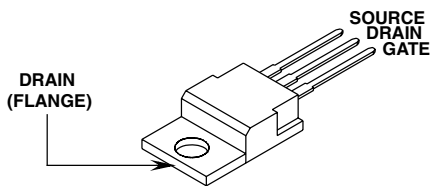
- 19A, 55V
- Simulation Models
 - Temperature Compensated PSPICE® and SABER™ Models
 - SPICE and SABER Thermal Impedance Models Available on the WEB at: www.Intersil.com
- Peak Current vs Pulse Width Curve
- UIS Rating Curve
- Related Literature
 - TB334, "Guidelines for Soldering Surface Mount Components to PC Boards"

Symbol

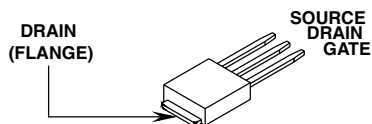


Packaging

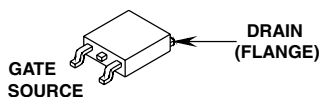
JEDEC STYLE TO-220AB



JEDEC TO-251AA



JEDEC TO-252AA



Product reliability information can be found at <http://www.mtp.intersil.com/reliability.html>

For severe environments, see our Automotive HUFA series.

All Intersil semiconductor products are manufactured, assembled and tested under ISO9000 and QS9000 quality systems certification.

HUF75309P3, HUF75309D3, HUF75309D3S

Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, Unless Otherwise Specified

			UNITS
Drain to Source Voltage (Note 1)	V_{DSS}	55	V
Drain to Gate Voltage ($R_{GS} = 20k\Omega$) (Note 1)	V_{DGR}	55	V
Gate to Source Voltage	V_{GS}	± 20	V
Drain Current			
Continuous (Figure 2)	I_D	19	A
Pulsed Drain Current	I_{DM}	Figure 4	
Pulsed Avalanche Rating	E_{AS}	Figures 6, 14, 15	
Power Dissipation	P_D	55	W
Derate Above 25°C		0.37	W/ $^\circ\text{C}$
Operating and Storage Temperature	T_J, T_{STG}	-55 to 175	$^\circ\text{C}$
Maximum Temperature for Soldering			
Leads at 0.063in (1.6mm) from Case for 10s.	T_L	300	$^\circ\text{C}$
Package Body for 10s, See Techbrief 334	T_{pkg}	260	$^\circ\text{C}$

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. $T_J = 25^\circ\text{C}$ to 150°C .

Electrical Specifications $T_C = 25^\circ\text{C}$, Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS	
OFF STATE SPECIFICATIONS							
Drain to Source Breakdown Voltage	BV_{DSS}	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$ (Figure 11)	55	-	-	V	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 50\text{V}, V_{GS} = 0\text{V}$	-	-	1	μA	
		$V_{DS} = 45\text{V}, V_{GS} = 0\text{V}, T_C = 150^\circ\text{C}$	-	-	250	μA	
Gate to Source Leakage Current	I_{GSS}	$V_{GS} = \pm 20\text{V}$	-	-	± 100	nA	
ON STATE SPECIFICATIONS							
Gate to Source Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\mu\text{A}$ (Figure 10)	2	-	4	V	
Drain to Source On Resistance	$r_{DS(ON)}$	$I_D = 19\text{A}, V_{GS} = 10\text{V}$ (Figure 9)	-	0.060	0.070	Ω	
THERMAL SPECIFICATIONS							
Thermal Resistance Junction to Case	$R_{\theta JC}$	(Figure 3)	-	-	2.7	$^\circ\text{C}/\text{W}$	
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	TO-220	-	-	62	$^\circ\text{C}/\text{W}$	
		TO-251, TO-252	-	-	100	$^\circ\text{C}/\text{W}$	
SWITCHING SPECIFICATIONS ($V_{GS} = 10\text{V}$)							
Turn-On Time	t_{ON}	$V_{DD} = 30\text{V}, I_D \cong 19\text{A},$ $R_L = 1.58\Omega, V_{GS} = 10\text{V},$ $R_{GS} = 27\Omega$	-	-	70	ns	
Turn-On Delay Time	$t_{d(ON)}$		-	7	-	ns	
Rise Time	t_r		-	39	-	ns	
Turn-Off Delay Time	$t_{d(OFF)}$		-	24	-	ns	
Fall Time	t_f		-	30	-	ns	
Turn-Off Time	t_{OFF}		-	-	80	ns	
GATE CHARGE SPECIFICATIONS							
Total Gate Charge	$Q_g(TOT)$	$V_{GS} = 0\text{V}$ to 20V	$V_{DD} = 30\text{V},$ $I_D \cong 19\text{A},$ $R_L = 1.58\Omega$ $I_g(REF) = 1.0\text{mA}$ (Figure 13)	-	20	24	nC
Gate Charge at 10V	$Q_g(10)$	$V_{GS} = 0\text{V}$ to 10V		-	11	13.5	nC
Threshold Gate Charge	$Q_g(TH)$	$V_{GS} = 0\text{V}$ to 2V		-	0.68	0.85	nC
Gate to Source Gate Charge	Q_{gs}			-	1.8	-	nC
Reverse Transfer Capacitance	Q_{gd}			-	5	-	nC

HUF75309P3, HUF75309D3, HUF75309D3S

Electrical Specifications $T_C = 25^\circ\text{C}$, Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
CAPACITANCE SPECIFICATIONS						
Input Capacitance	C_{ISS}	$V_{DS} = 25\text{V}, V_{GS} = 0\text{V},$ $f = 1\text{MHz}$ (Figure 12)	-	350	-	pF
Output Capacitance	C_{OSS}		-	150	-	pF
Reverse Transfer Capacitance	C_{RSS}		-	39	-	pF

Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Source to Drain Diode Voltage	V_{SD}	$I_{SD} = 19\text{A}$	-	-	1.25	V
Reverse Recovery Time	t_{rr}	$I_{SD} = 19\text{A}, dI_{SD}/dt = 100\text{A}/\mu\text{s}$	-	-	50	ns
Reverse Recovered Charge	Q_{RR}	$I_{SD} = 19\text{A}, dI_{SD}/dt = 100\text{A}/\mu\text{s}$	-	-	70	nC

Typical Performance Curves

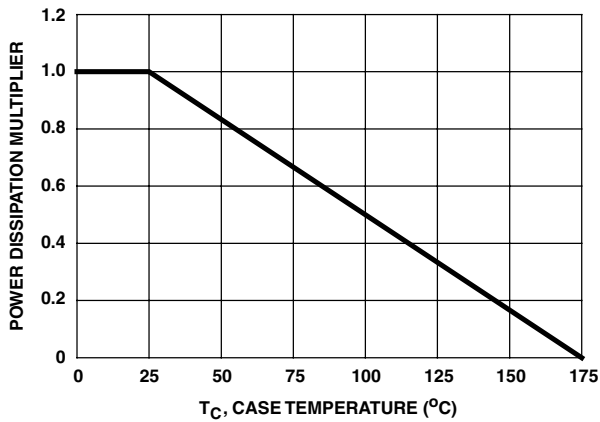


FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

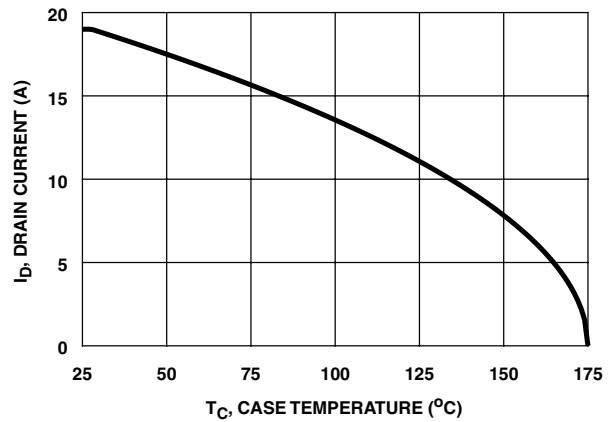


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

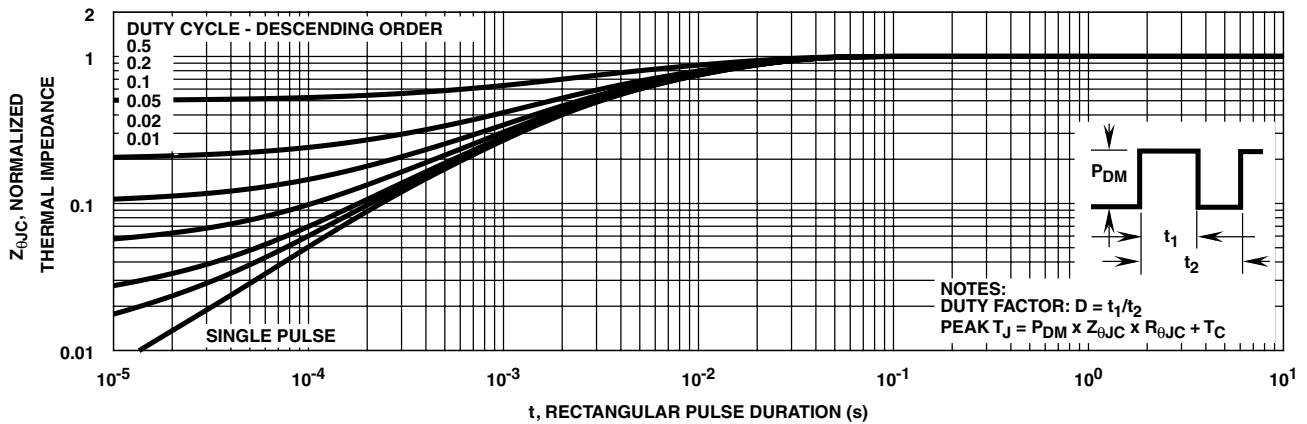


FIGURE 3. NORMALIZED MAXIMUM TRANSIENT THERMAL IMPEDANCE

Typical Performance Curves (Continued)

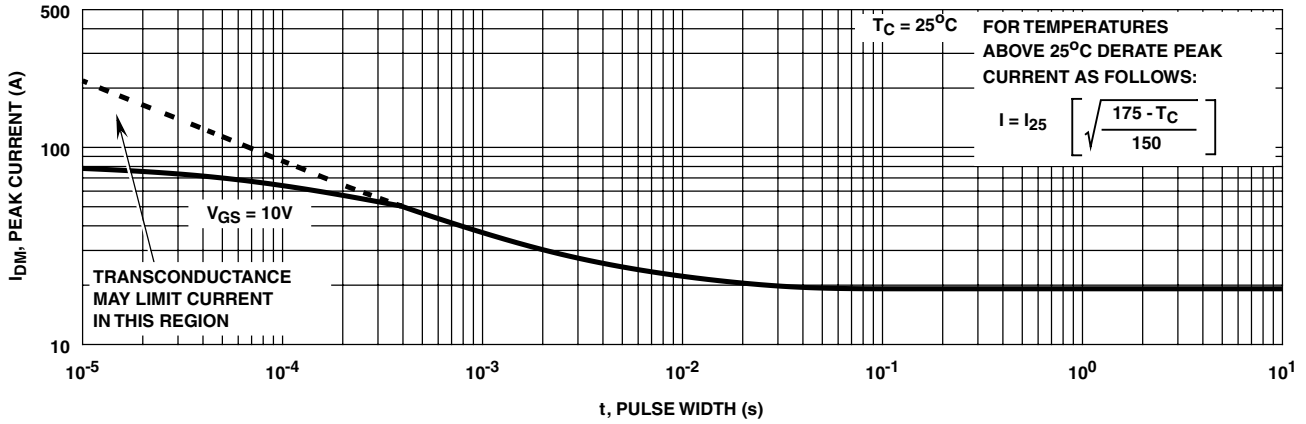


FIGURE 4. PEAK CURRENT CAPABILITY

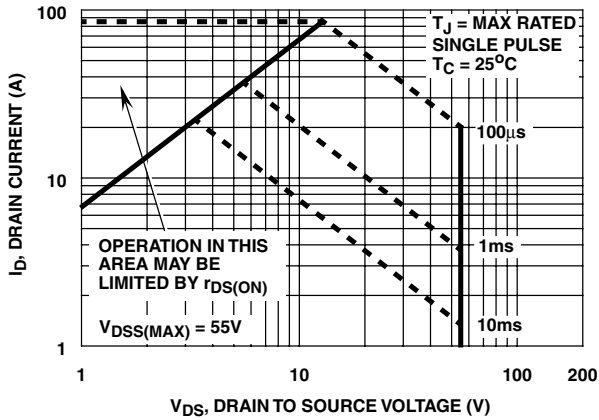
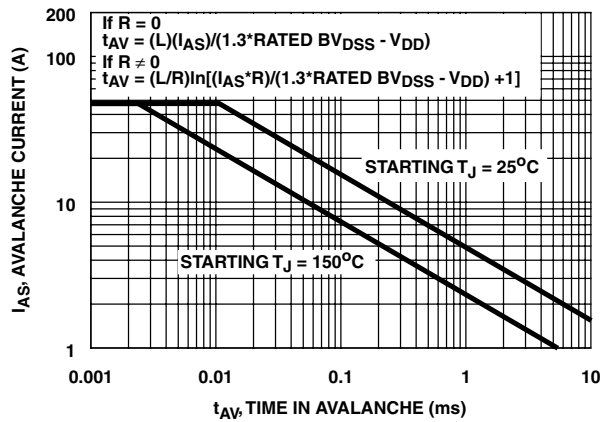


FIGURE 5. FORWARD BIAS SAFE OPERATING AREA



NOTE: Refer to Intersil Application Notes AN9321 and AN9322.

FIGURE 6. UNCLAMPED INDUCTIVE SWITCHING CAPABILITY

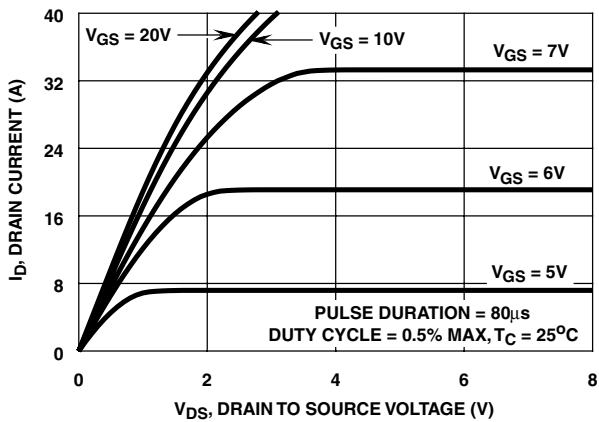


FIGURE 7. SATURATION CHARACTERISTICS

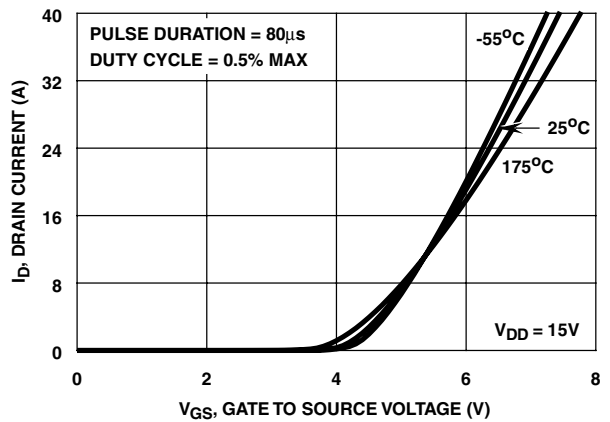


FIGURE 8. TRANSFER CHARACTERISTICS

Typical Performance Curves (Continued)

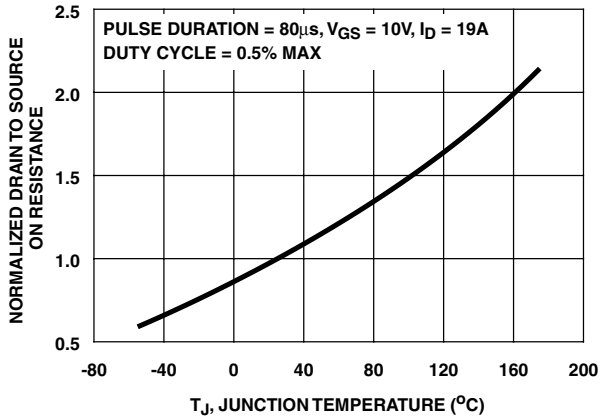


FIGURE 9. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs JUNCTION TEMPERATURE

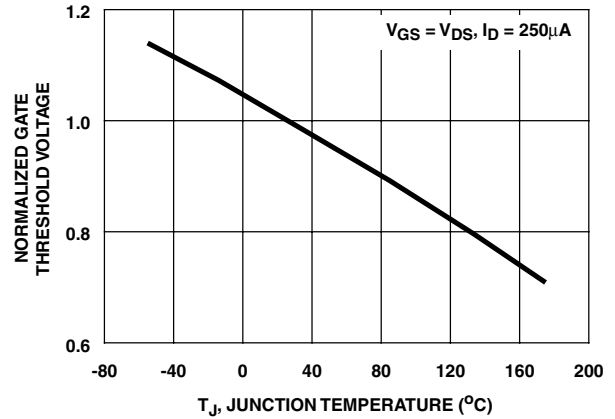


FIGURE 10. NORMALIZED GATE THRESHOLD VOLTAGE vs JUNCTION TEMPERATURE

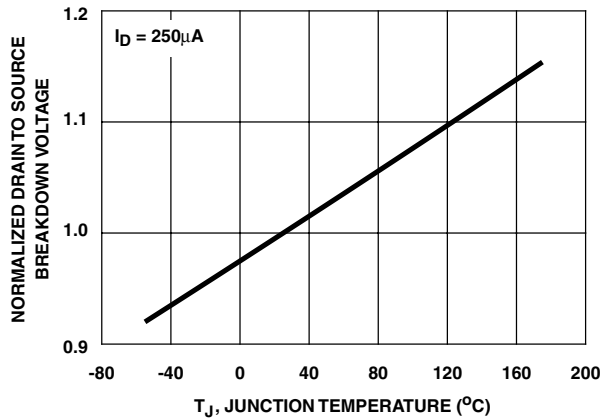


FIGURE 11. NORMALIZED DRAIN TO SOURCE BREAKDOWN VOLTAGE vs JUNCTION TEMPERATURE

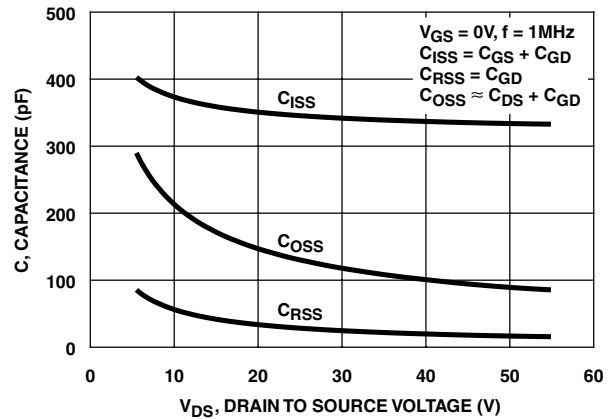
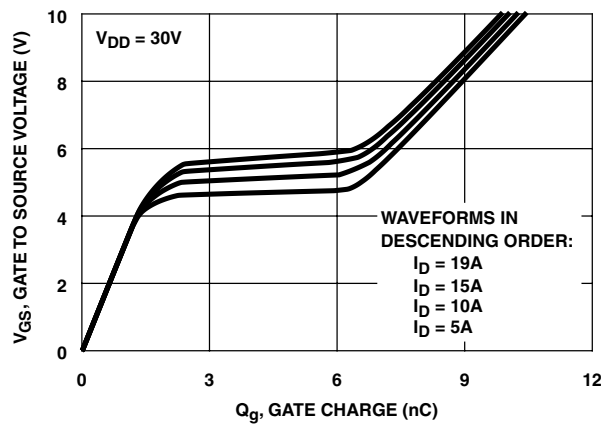


FIGURE 12. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE



NOTE: Refer to Intersil Application Notes AN7254 and AN7260.

FIGURE 13. GATE CHARGE WAVEFORMS FOR CONSTANT GATE CURRENT

Test Circuits and Waveforms

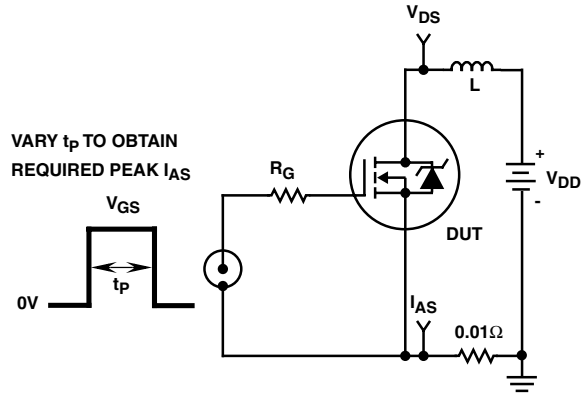


FIGURE 14. UNCLAMPED ENERGY TEST CIRCUIT

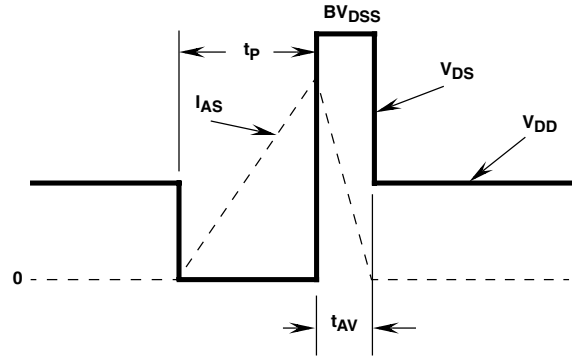


FIGURE 15. UNCLAMPED ENERGY WAVEFORMS

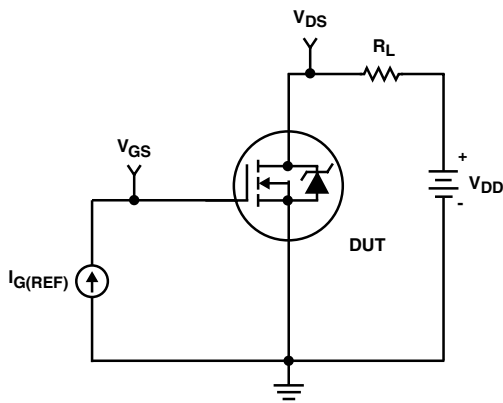


FIGURE 16. GATE CHARGE TEST CIRCUIT

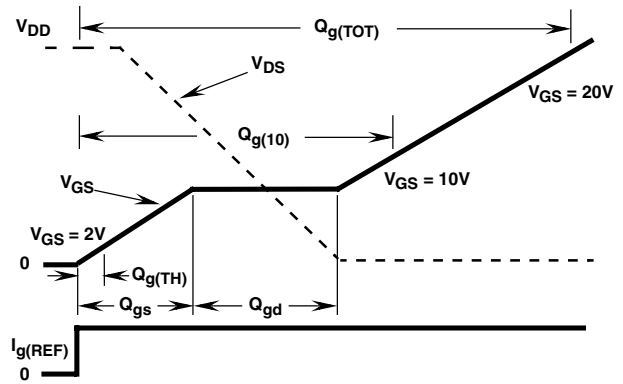


FIGURE 17. GATE CHARGE WAVEFORM

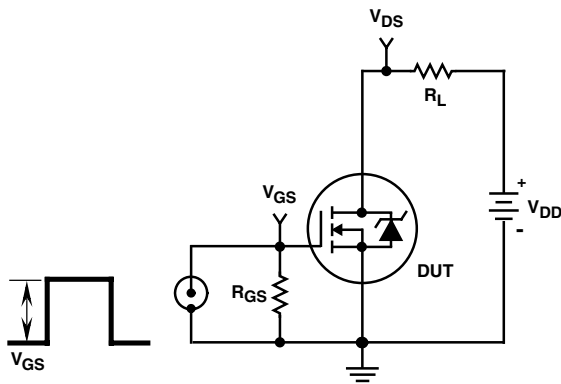


FIGURE 18. SWITCHING TIME TEST CIRCUIT

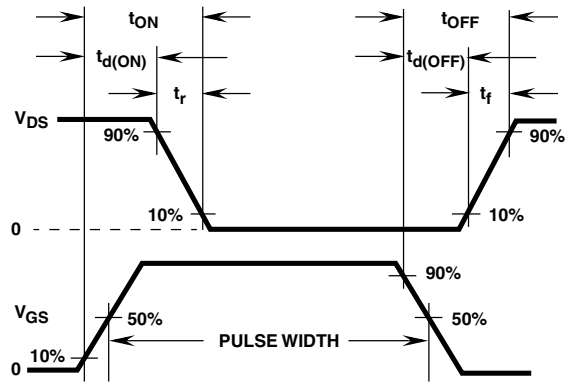


FIGURE 19. RESISTIVE SWITCHING WAVEFORMS

HUF75309P3, HUF75309D3, HUF75309D3S

PSPICE Electrical Model

.SUBCKT HUF75309 2 1 3 ; rev 30June97

CA 12 8 3.85e-10
 CB 15 14 4.15e-10
 CIN 6 8 3.17e-10

DBODY 7 5 DBODYMOD
 DBREAK 5 11 DBREAKMOD
 DPLCAP 10 5 DPLCAPMOD

EBREAK 11 7 17 18 59.22
 EDS 14 8 5 8 1
 EGS 13 8 6 8 1
 ESG 6 10 6 8 1
 EVTHRES 6 21 19 8 1
 EVTEMP 20 6 18 22 1

IT 8 17 1

LDRAIN 2 5 1e-9
 LGATE 1 9 2.24e-9
 LSOURCE 3 7 2.09e-9

MMED 16 6 8 8 MMEDMOD
 MSTRO 16 6 8 8 MSTROMOD
 MWEAK 16 21 8 8 MWEAKMOD

RBREAK 17 18 RBREAKMOD 1
 RDRAIN 50 16 RDRAINMOD 9.1e-3
 RGATE 9 20 1.27
 RLDRAIN 2 5 10
 RLGATE 1 9 22.4
 RLSOURCE 3 7 20.9
 RSLC1 5 51 RSLCMOD 1e-6
 RSLC2 5 50 1e3
 RSOURCE 8 7 RSOURCEMOD 4.0e-3
 RVTHRES 22 8 RVTHRESMOD 1
 RVTEMP 18 19 RVTEMPMOD 1

S1A 6 12 13 8 S1AMOD
 S1B 13 12 13 8 S1BMOD
 S2A 6 15 14 13 S2AMOD
 S2B 13 15 14 13 S2BMOD

VBAT 22 19 DC 1

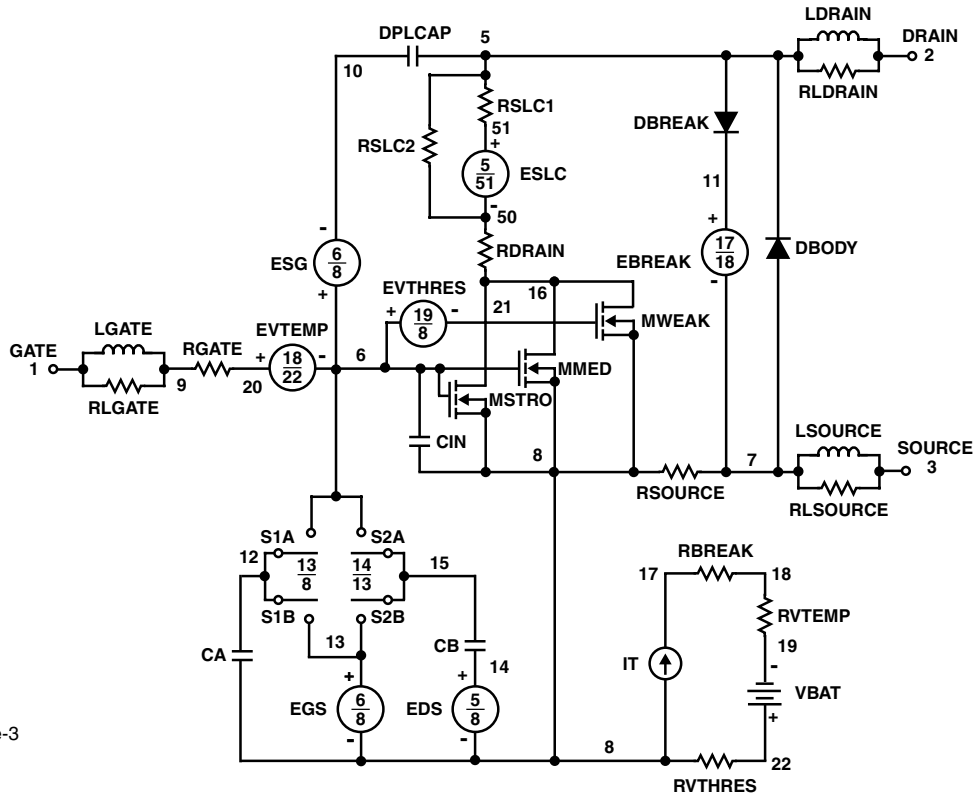
ESLC 51 50 VALUE={{(V(5,51)/ABS(V(5,51)))^(PWR(V(5,51))/(1e-6*43),4.5))}}

.MODEL DBODYMOD D (IS = 3.0e-13 RS = 1.04e-2 TRS1 = 1.89e-3 TRS2 = 0 CJO = 5.25e-10 TT = 3.09e-8 M = 0.5)
 .MODEL DBREAKMOD D (RS = 2.66e-1 TRS1 = 1.31e-4 TRS2 = 1.34e-5)
 .MODEL DPLCAPMOD D (CJO = 3.8e-10 IS = 1e-30 N = 10 M = 0.79)
 .MODEL MMEDMOD NMOS (VTO = 3.45 KP = 2 IS = 1e-30 N = 10 TOX = 1 L = 1u W = 1u RG = 1.27)
 .MODEL MSTROMOD NMOS (VTO = 3.95 KP = 19 IS = 1e-30 N = 10 TOX = 1 L = 1u W = 1u)
 .MODEL MWEAKMOD NMOS (VTO = 3.05 KP = 0.05 IS = 1e-30 N = 10 TOX = 1 L = 1u W = 1u RG = 12.7 RS = 0.1)
 .MODEL RBREAKMOD RES (TC1 = 1.05e-3 TC2 = 1.21e-7)
 .MODEL RDRAINMOD RES (TC1 = 3.1e-2 TC2 = 3.7e-5)
 .MODEL RSLCMOD RES (TC1 = 2.71e-3 TC2 = 1.07e-5)
 .MODEL RSOURCEMOD RES (TC1 = 0 TC2 = 0)
 .MODEL RVTHRESMOD RES (TC = -3.31e-3 TC2 = -4.31e-6)
 .MODEL RVTEMPMOD RES (TC1 = -1.62e-3 TC2 = 1.29e-6)

.MODEL S1AMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -6.0 VOFF = -3.0)
 .MODEL S1BMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -3.0 VOFF = -6.0)
 .MODEL S2AMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = 1.9 VOFF = 4.9)
 .MODEL S2BMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = 4.9 VOFF = 1.9)

.ENDS

NOTE: For further discussion of the PSPICE model, consult **A New PSPICE Sub-Circuit for the Power MOSFET Featuring Global Temperature Options**; IEEE Power Electronics Specialist Conference Records, 1991, written by William J. Hepp and C. Frank Wheatley.



HUF75309P3, HUF75309D3, HUF75309D3S

SPICE Thermal Model

REV February 1999

HUF75309

CTHERM1 th 6 8e-4
 CHERM2 6 5 1e-3
 CHERM3 5 4 2e-3
 CHERM4 4 3 2.8e-3
 CHERM5 3 2 5.5e-3
 CHERM6 2 tl 1.6e-2

RHERM1 th 6 1e-3
 RHERM2 6 5 7e-3
 RHERM3 5 4 9e-2
 RHERM4 4 3 4e-1
 RHERM5 3 2 6e-1
 RHERM6 2 tl 9.5e-1

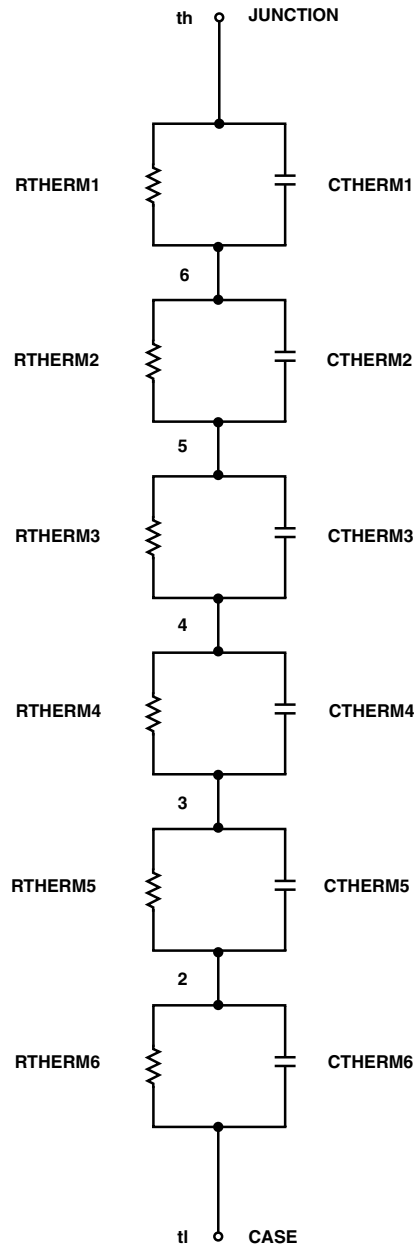
SABER Thermal Model

SABER thermal model HUF75309

template thermal_model th tl
 thermal_c th, tl

```
{
ctherm.ctherm1 th 6 = 8e-4
ctherm.ctherm2 6 5 = 1e-3
ctherm.ctherm3 5 4 = 2e-3
ctherm.ctherm4 4 3 = 2.8e-3
ctherm.ctherm5 3 2 = 5.5e-3
ctherm.ctherm6 2 tl = 1.6e-2
```

```
rtherm.rtherm1 th 6 = 1e-3
rtherm.rtherm2 6 5 = 7e-3
rtherm.rtherm3 5 4 = 9e-2
rtherm.rtherm4 4 3 = 4e-1
rtherm.rtherm5 3 2 = 6e-1
rtherm.rtherm6 2 tl = 9.5e-1
}
```



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Bottomless TM	FAST _r TM	POP TM	SuperSOT TM -6
CoolFET TM	GlobalOptoisolator TM	PowerTrench [®]	SuperSOT TM -8
CROSSVOLT TM	GTO TM	QFET TM	SyncFET TM
DenseTrench TM	HiSeC TM	QS TM	TinyLogic TM
DOMET TM	ISOPLANAR TM	QT Optoelectronics TM	UHC TM
EcoSPARK TM	LittleFET TM	Quiet Series TM	UltraFET TM
E ² CMOS TM	MicroFET TM	SILENT SWITCHER [®]	VCX TM
EnSigna TM	MICROWIRE TM	SMART START TM	
FACT TM	OPTOLOGIC TM	Star* Power TM	
FACT Quiet Series TM	OPTOPLANAR TM	Stealth TM	

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

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